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APPLICATION DATA SHEET

(1) APPLICANT INFORMATION

First Inventor Steve M. Danziger
Residence Manassas, Virginia
Mailing Address 10100 Tasker Drive
Manassas, VA 20109
USA

Citizenship USA

Second Inventor Tushar Shah
Residence Columbia, Maryland
Mailing Address 6417 River Run
Columbia, MD 21044
USA

Citizenship USA

(2) CORRESPONDENCE INFORMATION

Ronald R. Snider
Snider & Associates
P.O. Box 27613
Washington, DC 20038-7613

102240-4822360

(3) APPLICANT INFORMATION

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(4) REPRESENTATIVE INFORMATION

Ronald R. Snider Reg. # 24,962
Peter N. Lalos Reg. # 19,789
Francis A. Keegan Reg. # 19,245

(5) DOMESTIC PRIORITY INFORMATION

This case is a Divisional of USPTO Serial Number 09/321,565, filed May 28, 1999 and issuing as US Patent No. 6,221,682 on April 24, 2001.

(6) FOREIGN PRIORITY INFORMATION

None

(7) ASSIGNEE INFORMATION

Name BAE SYSTEMS - Information & Electronic Warfare Systems
Address 9300 Wellington Road
Manassas, VA 20110-4122